

## LAMINATES AND MORE FOR PCB

### *Copper Clad Laminates*

#### *ZD-68, ZD 95*

**Description:** Glass–paper epoxy composite. It can be processed by both punching and drilling and is especially suitable for STH (Silver Through Hole). It's excellent thermal resistance makes it especially suitable for lead-free processes, carbon ink printing, hot air leveling and Ni/Au finishes.

Moreover, it is listed by UL 94 V-0 (E222366).

## ZD – 68(G)F, ZD-95(G)F

### Copper clad laminates

#### Properties

NO	Item	Unit	Index		Typical Value	
			ZD-68(G)F	ZD-95(G)F ZD-95 FH	ZD-68(G)F	ZD-95(G)F
1	Peel Strength, A. After Thermal Stress B. At 105°C	N/m m	1.25 0.80	1.05 -	2.0 1.9	1.8 -
2	Volume Resistivity, A. C-96/35/90 B. At High Temperature E- 24/125	MΩ* cm	10 <sup>4</sup> -	10 <sup>5</sup> 10 <sup>3</sup>	10 <sup>5</sup> -	10 <sup>7</sup> 10 <sup>3</sup>
3	Surface Resistivity > A. C-96/35/90 B At High Temperature E- 24/125	M Ω	10 <sup>3</sup> -	10 <sup>4</sup> 10 <sup>3</sup>	10 <sup>4</sup> -	10 <sup>4</sup> 10 <sup>3</sup>
4	Water Absorption	%	1.0	0.5	0.8	0.4
5	Dielectric Breakdown	Kv	30	40	35	43
6	Permittivity, 1 MHz	-	4.8	5.4	4.5	5.0
7	Dissipation Factor, 1MHz	-	0.04	0.035	0.038	0.035

## ZD – 68(G)F, ZD-95(G)F

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8	Flexural Strength, A Lengthwise B Crosswise	MPa	138 111	207 172	270 240	260 260
9	Arc Resistance	S	20	60	20	60
10	Thermal Stress At 260°C, 10s	-	No Delaminating and Blistering			
11	Flammability	-	V-1	UL 94 V-0	V-1	UL 94 V-0
12	CTI		400v only ZD-95 (G) FH		400v only ZD-95 (G) FH	

**Note:**

1. Test methods are in accordance with GB/T4722.
2. Typical values are stable values tested by our company. But they can't be used as guaranteed values. If required they can be negotiated by us.

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